



SOT353-1

plastic thin shrink small outline package; 5 leads; body width
1.25 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP5
Package type industry code	TSSOP5
Package style descriptive code	TSSOP (thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-203
JEITA package outline code	SC-88A
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.85	-	2.05	2.25	mm
E	package width		1.15	-	1.25	1.35	mm
A	seated height		[tbd]	-	1.1	1.1	mm
A ₂	package height		0.8	-	0.9	1	mm
e	nominal pitch		-	-	[tbd]	-	mm
n ₂	actual quantity of termination		-	-	5	-	

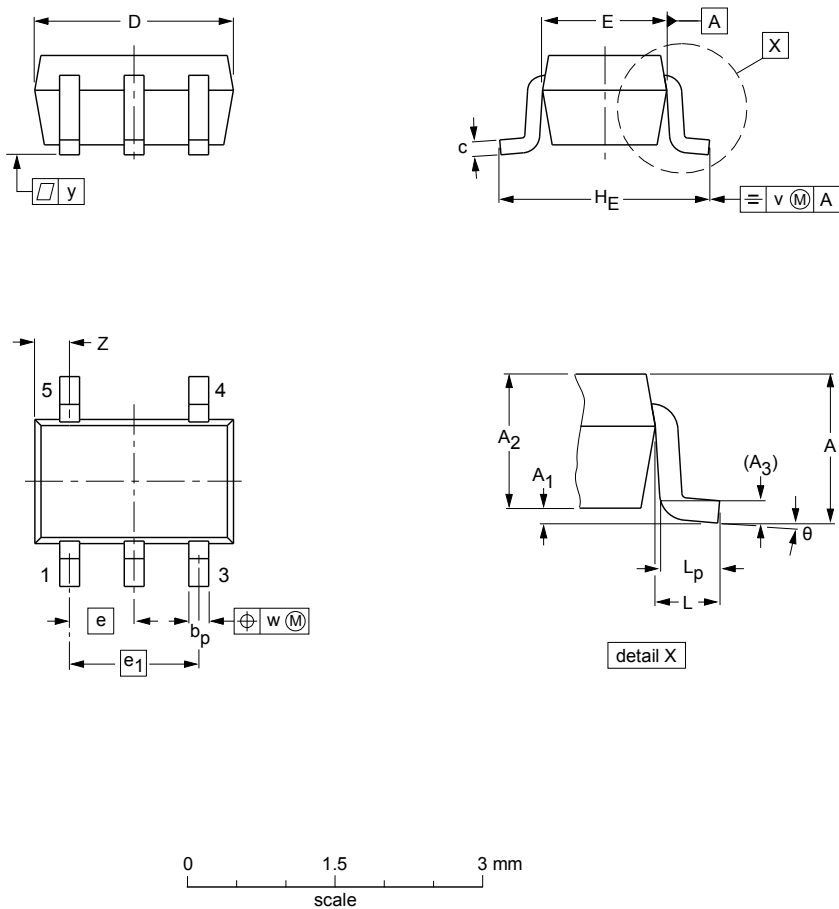


plastic thin shrink small outline package; 5
leads; body width 1.25 mm

2. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.1 0	1.0 0.8	0.15	0.30 0.15	0.25 0.08	2.25 1.85	1.35 1.15	0.65	1.3	2.25 2.0	0.425	0.46 0.21	0.3	0.1	0.1	0.60 0.15	7° 0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT353-1		MO-203	SC-88A			00-09-01 03-02-19

Fig. 1. Package outline TSSOP5 (SOT353-1)

3. Legal information

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